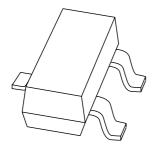
DISCRETE SEMICONDUCTORS

DATA SHEET



BCW69; BCW70 PNP general purpose transistors

Product specification Supersedes data of 1999 Apr 19 2004 Feb 06





PNP general purpose transistors

BCW69; BCW70

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 45 V).

APPLICATIONS

· General purpose switching and amplification.

DESCRIPTION

PNP transistor in a SOT23 plastic package. NPN complements: BCW71 and BCW72.

MARKING

TYPE NUMBER	MARKING CODE(1)
BCW69	H1*
BCW70	H2*

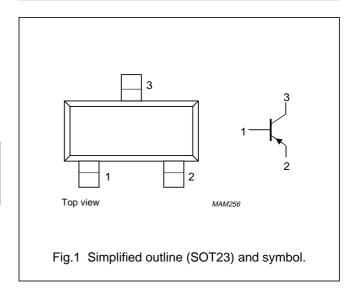
Note

1. * = p : Made in Hong Kong.

* = t : Made in Malaysia. * = W : Made in China.

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



ORDERING INFORMATION

TYPE	PACKAGE				
NUMBER	NAME	NAME DESCRIPTION VERSI			
BCW69	_	 plastic surface mounted package; 3 leads 			
BCW70					

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base; I _C = −2 mA	_	-45	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
I _C	collector current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-200	mA
I _{BM}	peak base current		_	-200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Philips Semiconductors Product specification

PNP general purpose transistors

BCW69; BCW70

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = -20 V	_	_	-100	nA
		$I_E = 0$; $V_{CB} = -20 \text{ V}$; $T_j = 100 ^{\circ}\text{C}$	_	_	-10	μΑ
I _{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = -5 \text{ V}$	_	_	-100	nA
h _{FE}	DC current gain	$I_C = -10 \mu\text{A}; V_{CE} = -5 \text{V}$				
	BCW69		_	90	_	
	BCW70		_	150	_	
	DC current gain	$I_C = -2 \text{ mA}; V_{CE} = -5 \text{ V}$				
	BCW69		120	-	260	
	BCW70		215	-	500	
V _{CEsat}	collector-emitter saturation	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	-80	-300	mV
	voltage	$I_C = -50 \text{ mA}$; $I_B = -2.5 \text{ mA}$; note 1	_	-150	_	mV
V _{BEsat}	base-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	-720	-	mV
		$I_C = -50 \text{ mA}$; $I_B = -2.5 \text{ mA}$; note 1	_	-810	_	mV
V _{BE}	base-emitter voltage	$I_C = -2 \text{ mA}; V_{CE} = -5 \text{ V}$	-600	_	-750	mV
C _c	collector capacitance	I _E = I _e = 0; V _{CB} = -10 V; f = 1 MHz	_	4.5	_	pF
f _T	transition frequency	$I_C = -10 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz		_	_	MHz
F	noise figure	$I_C = -200 \mu A; V_{CE} = -5 V;$ $R_S = 2 k\Omega; f = 1 kHz; B = 200 Hz$	_	_	10	dB

Note

1. Pulse test: $t_p \le 300 \ \mu s; \ \delta \le 0.02$.

Philips Semiconductors Product specification

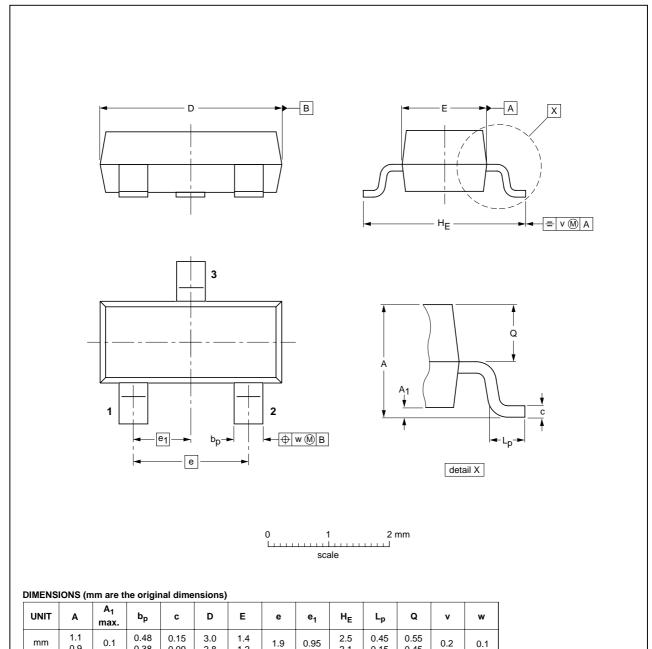
PNP general purpose transistors

BCW69; BCW70

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC EIAJ PROJECTION		PROJECTION	ISSUE DATE		
SOT23		TO-236AB				-97-02-28- 99-09-13

Philips Semiconductors Product specification

PNP general purpose transistors

BCW69; BCW70

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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